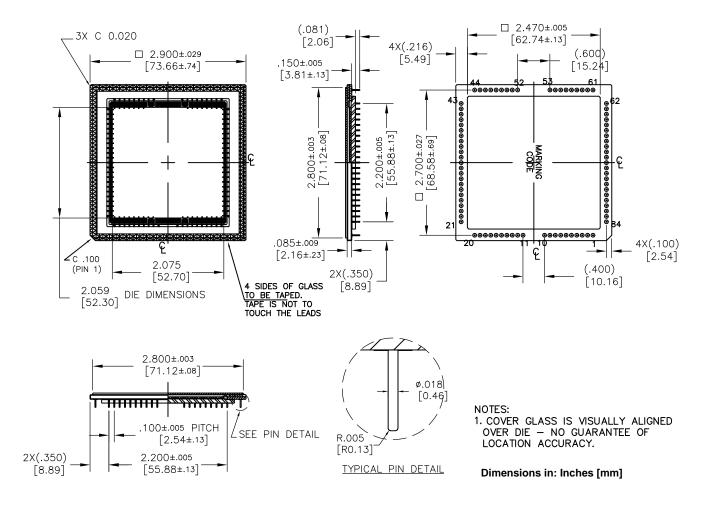
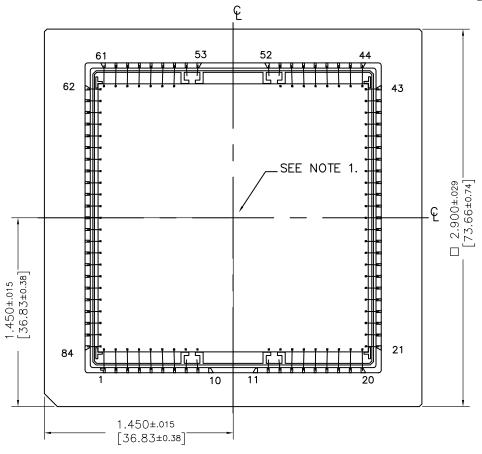
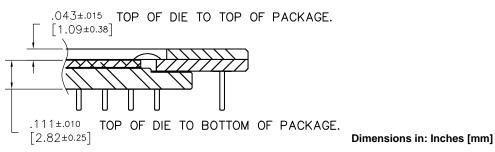
## CPGA84, 73.66x73.66 CASE 107EU ISSUE O

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